

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seung Hee HAN</td> <td>10/07/2011</td> </tr> <tr> <td>Hyun Soo KO</td> <td>10/07/2011</td> </tr> <tr> <td>Jae Hoon CHUNG</td> <td>10/07/2011</td> </tr> <tr> <td>Moon Il LEE</td> <td>11/30/2011</td> </tr> </tbody> </table>		Name	Execution Date	Seung Hee HAN	10/07/2011	Hyun Soo KO	10/07/2011	Jae Hoon CHUNG	10/07/2011	Moon Il LEE	11/30/2011
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RECEIVING PARTY DATA											
Name:	LG Electronics Inc.										
Street Address:	20 Yeouido-dong, Yeongdeungpo-gu										
City:	Seoul										
State/Country:	REPUBLIC OF KOREA										
Postal Code:	150-721										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13380498</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13380498						
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CORRESPONDENCE DATA											
Fax Number:	(213)623-2211										
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NAME OF SUBMITTER:	Harry S. Lee										
Total Attachments: 2 source=2101-5164-Assignment#page1.tif source=2101-5164-Assignment#page2.tif											

OP \$40.00 13380498

ASSIGNMENT

- (1-8) *Insert Name(s) of Inventor(s)* (1) HAN, Seung Hee (5)
- (2) KO, Hyun Soo (6)
- (3) CHUNG, Jae Hoon (7)
- (4) LEE, Moon Il (8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

- (9) *Insert name of Assignee* (9) LG ELECTRONICS INC.
- (10) *Insert state of Incorporation of Assignee* (10) Republic of Korea
- (11) *Insert address of Assignee* (11) 20 Yeouido-dong, Yeoungdeungpo-gu, Seoul 150-721 Republic of Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

- (12) *Insert identification of Invention, such as Title, Case Number or Foreign Application Number* (12) **METHOD AND APPARATUS FOR UPLINK TRANSMISSION IN A MULTI-ANTENNA SYSTEM**

(Application Serial No. )  
for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

- (13) *Insert Date of Signing of Application* (13)

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints the Attorneys Associated with Customer No. 035884 the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 7. Oct. 2011 Signature of Inventor [Signature]

Date: 7th. Oct. 2011. Signature of Inventor [Signature]

Date: 7 Oct., 2011 Signature of Inventor [Signature]

Date: \_\_\_\_\_ Signature of Inventor \_\_\_\_\_

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Date: 30 Nov, 2011 Signature of Inventor 